SCLS174E - MARCH 1984 - REVISED AUGUST 2003

- Operating Voltage Range of 4.5 V to 5.5 V
- High-Current Outputs Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-µA Max I<sub>CC</sub>
- Typical t<sub>pd</sub> = 12 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers

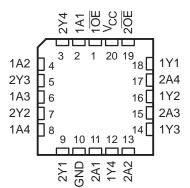
#### description/ordering information

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The 'HCT240 devices are organized as two 4-bit buffers/drivers with separate output-enable ( $\overline{OE}$ ) inputs. When  $\overline{OE}$  is low, the device passes inverted data from the A inputs to the Y outputs. When  $\overline{OE}$  is high, the outputs are in the high-impedance state.

SN54HCT24	0 J OR	W PACKAG	E
SN74HCT240 [	DW, N, NS,	OR PW PAG	CKAGE
	(TOP VIEW	/)	

		,	
1OE   1A1   2Y4   1A2   2Y3   1A3	4 5	20 19 18 17 16 15	V <sub>CC</sub>   2OE   1Y1   2A4   1Y2   2A3
2Y2		14	1Y3
1A4 [	8	13	2A2
2Y1 [	9	12	] 1Y4
GND	10	11	2A1

SN54HCT240 . . . FK PACKAGE (TOP VIEW)



#### **ORDERING INFORMATION**

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 20	SN74HCT240N	SN74HCT240N
		Tube of 25	SN74HCT240DW	1107240
	SOIC – DW	Reel of 2000	SN74HCT240DWR	HCT240
–40°C to 85°C	SOP – NS	Reel of 2000	SN74HCT240NSR	HCT240
		Tube of 70	SN74HCT240PW	
	TSSOP – PW	Reel of 2000	SN74HCT240PWR	HT240
		Reel of 250	SN74HCT240PWT	
	CDIP – J	Tube of 20	SNJ54HCT240J	SNJ54HCT240J
–55°C to 125°C	CFP – W	Tube of 85	SNJ54HCT240W	SNJ54HCT240W
	LCCC – FK	Tube of 55	SNJ54HCT240FK	SNJ54HCT240FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

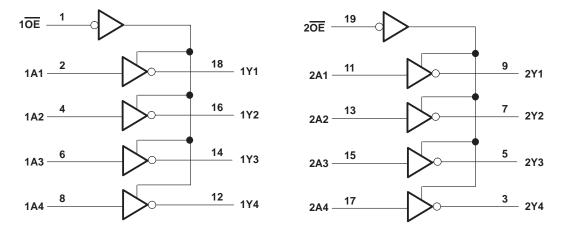


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FUNCTION TABLE (each buffer/driver)								
INPUTS OUTPUT								
OE	Α	Y						
L	Н	L						
L	L	Н						
Н	Х	Z						

#### logic diagram (positive logic)



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	$\ldots$ –0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note	1) ±20 mA
Output clamp current, $I_{OK}$ (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see	Note 1) ±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±35 mA
Continuous current through V <sub>CC</sub> or GND	±70 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DW p	ackage 58°C/W
N pac	kage 69°C/W
NŠ pa	ackage 60°C/W
PWp	ackage 83°C/W
Storage temperature range, T <sub>stg</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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#### recommended operating conditions (see Note 3)

			SN	SN54HCT240			SN74HCT240		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2			2			V
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V			0.8			0.8	V
VI	Input voltage		0		V <sub>CC</sub>	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
$\Delta t/\Delta v$	Input transition rise/fall time				500			500	ns
Т <sub>А</sub>	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS			T <sub>A</sub> = 25°C			SN54HCT240		SN74HCT240		
PARAMETER	TEST CO	v <sub>cc</sub>	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
Maria		I <sub>OH</sub> = -20 μA	45.1	4.4	4.499		4.4		4.4		
VOH	$V_{I} = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		V
N/	1/1 = 1/11 = 0r 1/11	I <sub>OL</sub> = 20 μA	4514		0.001	0.1		0.1		0.1	
VOL		$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	V
Ц	$V_I = V_{CC} \text{ or } 0$		5.5 V		±0.1	±100		±1000		±1000	nA
I <sub>OZ</sub>	$V_{O} = V_{CC} \text{ or } 0,$	$V_I = V_{IH} \text{ or } V_{IL}$	5.5 V		±0.01	±0.5		±10		±5	μA
ICC	$V_I = V_{CC} \text{ or } 0,$	IO = 0	5.5 V			8		160		80	μA
$\Delta I_{CC}^{\dagger}$	One input at 0.5 V Other inputs at 0 or		5.5 V		1.4	2.4		3		2.9	mA
Ci			4.5 V to 5.5 V		3	10		10		10	pF

<sup>†</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

## switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	N.	Τį	ς = 25°C	;	SN54H0	CT240	SN74H	CT240	UNUT
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	•	V	4.5 V		13	25		37		32	
<sup>t</sup> pd	A	Y	5.5 V		12	23		33		29	ns
	OE	Y	4.5 V		21	35		53		44	
<sup>t</sup> en	ÛE		5.5 V		19	32		48		40	ns
		Y	4.5 V		19	35		53		44	
<sup>t</sup> dis	OE		5.5 V		18	32		48		40	ns
tt		V	4.5 V		8	12		18		15	
		Ý	5.5 V		7	11		16		14	ns



## **SN54HCT240, SN74HCT240 OCTAL BUFFERS AND LINE DRIVERS** WITH 3-STATE OUTPUTS SCLS174E – MARCH 1984 – REVISED AUGUST 2003

# switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 1)

	FROM TO			T <sub>A</sub> = 25°C		;	SN54HCT240		SN74HCT240		
PARAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	•	V	4.5 V		20	42		63		53	
<sup>t</sup> pd	A	Y	5.5 V		19	38		56		48	ns
	t <sub>en</sub> OE	Y	4.5 V		25	52		79		65	
ten			5.5 V		22	47		71		59	ns
		V	4.5 V		17	42		63		53	
tt		ŕ	5.5 V		14	38		57		48	ns

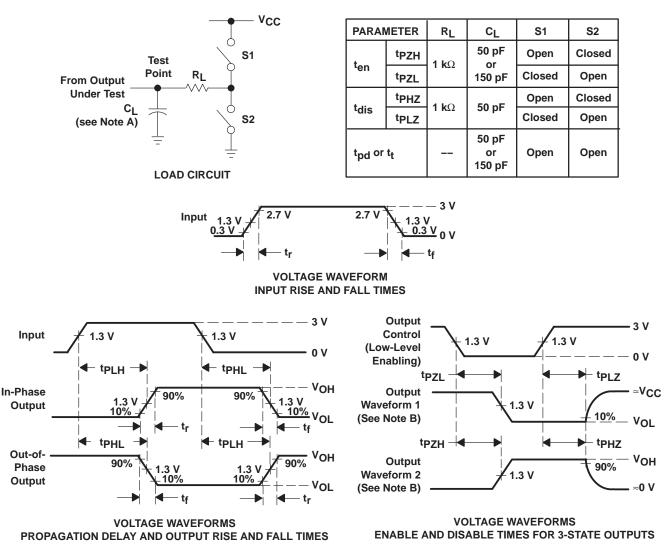
#### operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance	No load	40	pF



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#### PARAMETER MEASUREMENT INFORMATION



- NOTES: A. CL includes probe and test-fixture capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
    Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z<sub>Q</sub> = 50 Ω, t<sub>r</sub> = 6 ns, t<sub>f</sub> = 6 ns.
  - D. The outputs are measured one at a time with one input transition per measurement.
  - E. tpLZ and tpHZ are the same as tdis.
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G. tPLH and tPHL are the same as tpd.

#### Figure 1. Load Circuit and Voltage Waveforms



#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
85505012A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
8550501RA	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
JM38510/65753BRA	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
SN54HCT240J	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
SN74HCT240DW	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74HCT240DWR	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74HCT240N	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HCT240NSR	ACTIVE	SO	NS	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HCT240PW	ACTIVE	TSSOP	PW	20	70	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HCT240PWR	ACTIVE	TSSOP	PW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HCT240PWT	ACTIVE	TSSOP	PW	20	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SNJ54HCT240FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54HCT240J	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MLCC006B - OCTOBER 1996

#### FK (S-CQCC-N\*\*)

#### LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



## N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



#### MECHANICAL DATA

#### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



### **MECHANICAL DATA**

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

## PW (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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